Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3132

Chopper Regulator DC-DC Converter, and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 0.07 Ω (typ.)

• High forward transfer admittance $: |Y_{fs}| = 33 \text{ S (typ.)}$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 500 V)$

• Enhancement-mode : $V_{th} = 2.4 \sim 3.4 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	500	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
DCDrain current	DC (Note 1)	I _D	50	Α	
	Pulse (Note 1)	I _{DP}	200	Α	
Drain power dissipation	n (Tc = 25°C)	P _D	250	W	
Single pulse avalanche energy (Note 2)		E _{AS}	525	mJ	
Avalanche current		I _{AR}	50	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	25	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

20.5 max \$\display 3.3 \pm 0.2\$ 20.5 max \$\display 3.3 \pm 0.2\$

Weight: 9.75 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	35.7	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 357 μ H, R_G = 25 Ω , I_{AR} = 50 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

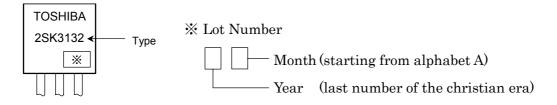
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I_{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_		V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	-	_	100	μΑ
Drain-source br	eakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	500	_	1	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.4	_	3.4	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 25 A		0.07	0.095	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 25 A	15	33	-	S
Input capacitano	e	C _{iss}		_	11000	_	
Reverse transfer	capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	2100	_	pF
Output capacitance		C _{oss}			4200	_	
Switching time	Rise time	tr	V_{GS} V_{GS} V_{GS} V_{OV} V_{DD} V_{DD}	_	105	1	
	Turn-on time	t _{on}		- 1	160		ne
	Fall time	t _f		ı	65	1	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{w}} = 10 \mu s$	_	245	_	
Total gate charg plus gate-drain)		Qg			280		
Gate-source charge		Q_{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		150	_	nC
Gate-drain ("mil	ler") charge	Q _{gd}		_	130	_	

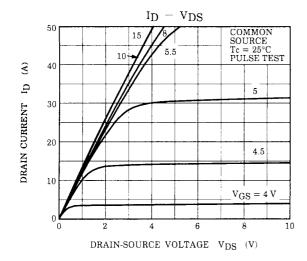
Source-Drain Ratings and Characteristics (Ta = 25°C)

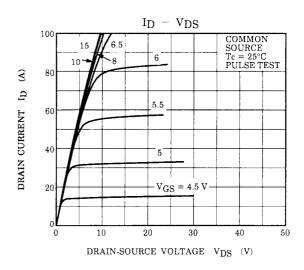
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	1	_	50	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	200	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 25 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 50 A, V _{GS} = 0 V		600		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 Å / μs		12	_	μC

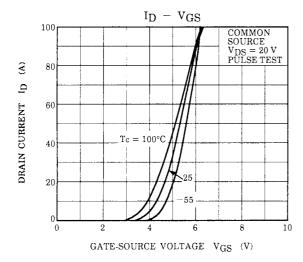
Marking

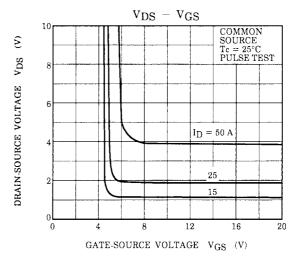


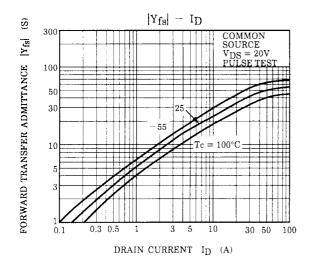
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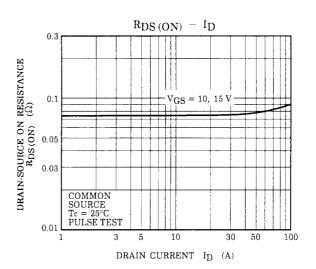




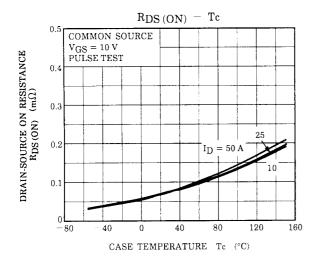


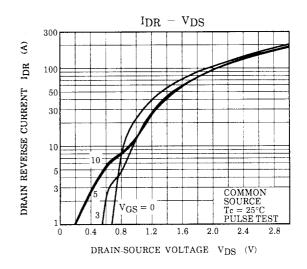


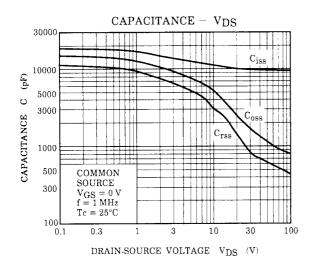


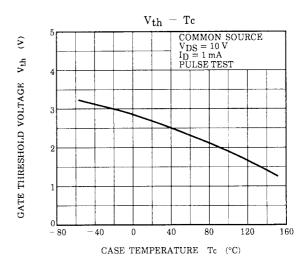


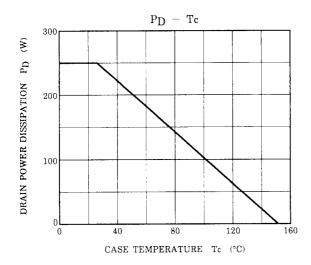
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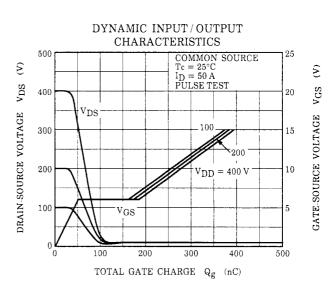




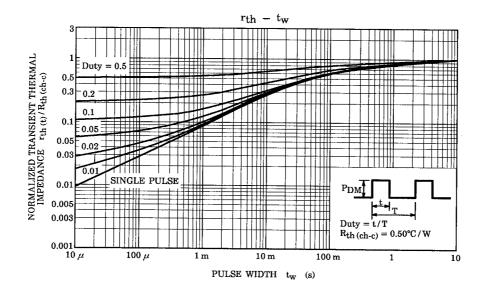


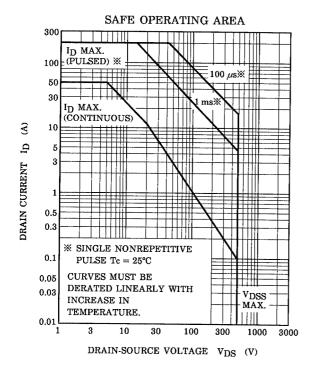


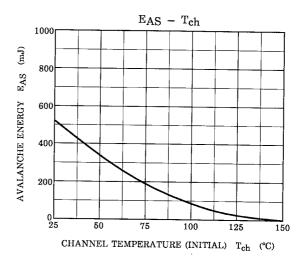


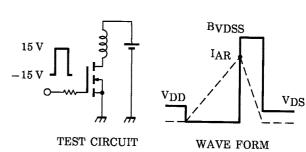


4









$$\begin{split} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 357~\mu H \end{split}$$

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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